



DATE 18 FEB 2014

А3

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION & APPLIES TO PLATED
 TERMINAL AND IS MEASURED BETWEEN
- 0.15 AND 0.30 MM FROM TERMINAL TIP. COPLANARITY APPLIES TO THE EXPOSED
- PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.80	1.00	
A1	0.00	0.05	
А3	0.20 REF		
b	0.20	0.30	
D	3.00 BSC		
D2	2.60	2.80	
Е	3.00 BSC		
E2	1.90	2.10	
е	0.50 BSC		
L	0.20	0.40	
L1		0.15	
L2	0.10 REF		
K	0.15 MIN		

GENERIC MARKING DIAGRAM*



= Assembly Location Α

= Wafer Lot 1 Υ = Year W = Work Week

= Pb-Free Package (Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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